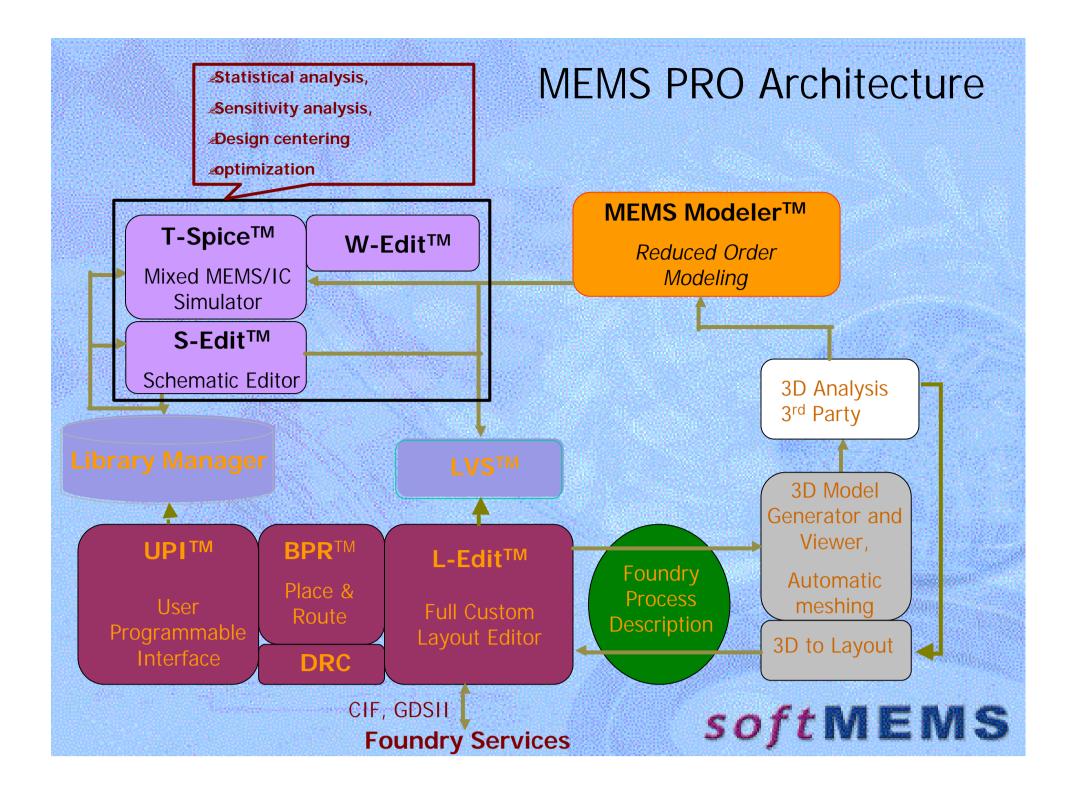
# An illustrated approach to DfM for MEMS by *soft* MEMS



#### Design for Manufacturing Tools through the design flow :

- •Schematic level / parameterized behavioral modeling level : -Monte Carlo analysis, sensitivity analysis, optimization (including IC design if necessary)
- •Layout :
  - -Test structures libraries
  - -Design verification (DRC, LVS)
- 3d model generation
  - -Cross section view and 3D inspection
  - -Quick generation of geometry and meshing allows faster multi-

simulations tasks -Model reduction for system level simulations

#### **SENSITIVITY ANALYSIS :**

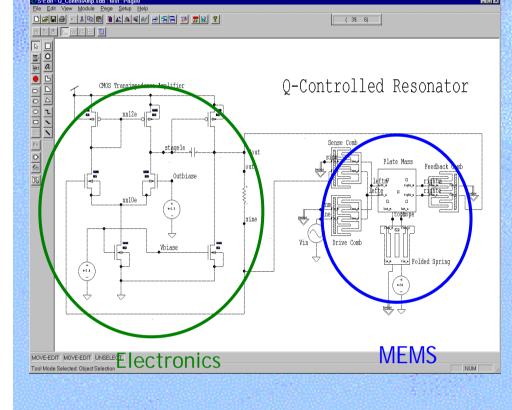
- Sensitivity calculation: parameters contribution to performance
- Sensitivity analysis is performed to investigate influence of individual parameters on the device behavior
- Easy set up : parameter sweep simulations
- May help designers to indicate to foundry what process parameters must be closely watched
- MEMS and IC models to take into account all process variations on :
  - Material properties,
  - Thermal coefficients,
  - Etch rate ratios, over-etch variations.

## Statistical Analysis

Statistical analysis based on process/mask variations - Incorporates statistical data from foundries into models

## **Combined MEMS & IC Schematics**

- Schematics can contain both IC and MEMS modules
  - IC modeled using standard IC models
- MEMS modeled using behavioral macro models
- Component library
  - Behavioral models for standard MEMS components



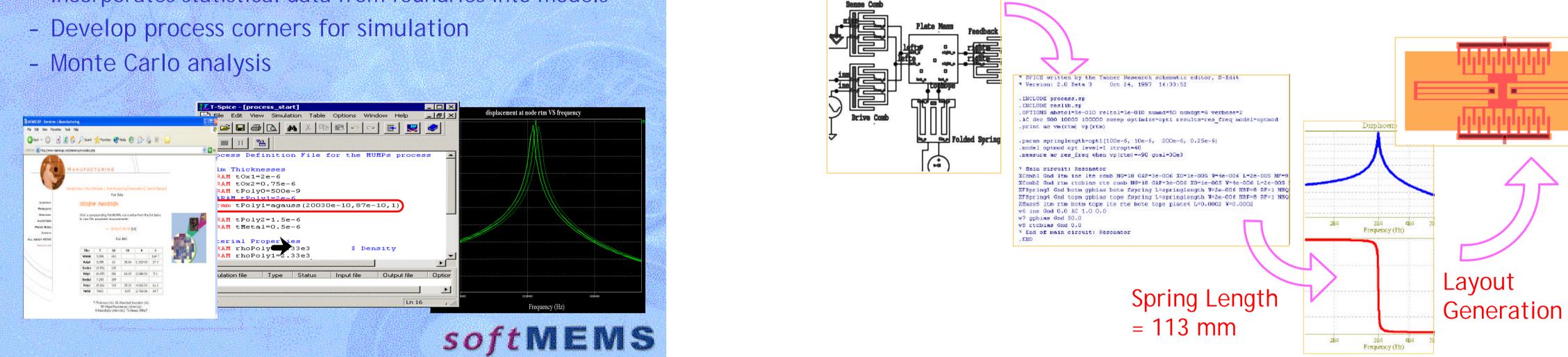
- Simulation of MEMS Macromodels at ODE Level
- Model Representation
  - Equivalent Circuit Models
  - Functional Models
  - Table Based Models
- Transient/DC/AC Analysis
- Parametric Analysis

### softMEMS

#### Optimization

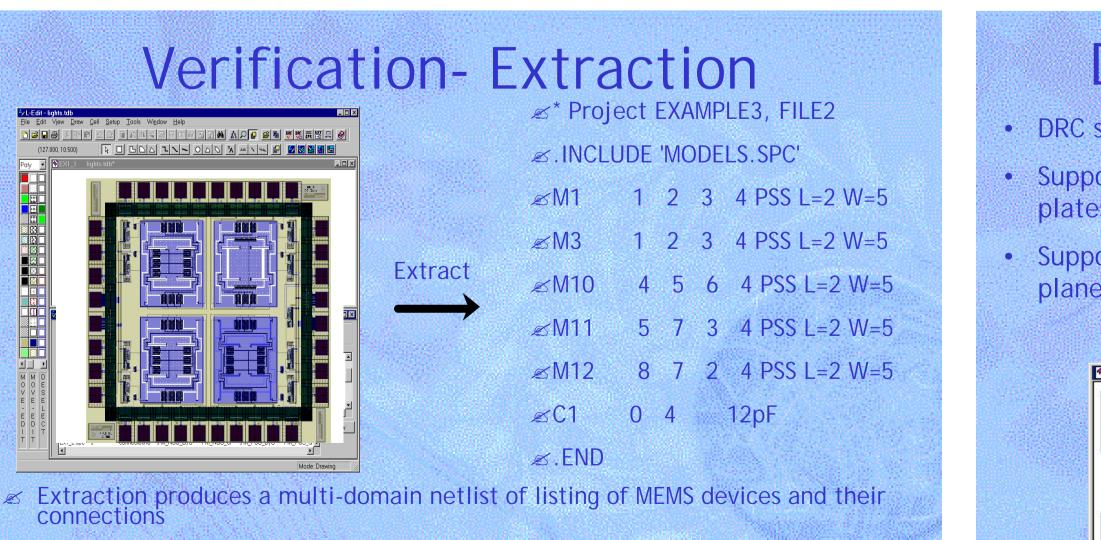
*Example*: Optimize springlength using mimimum area with resonant frequency = 30 KHz

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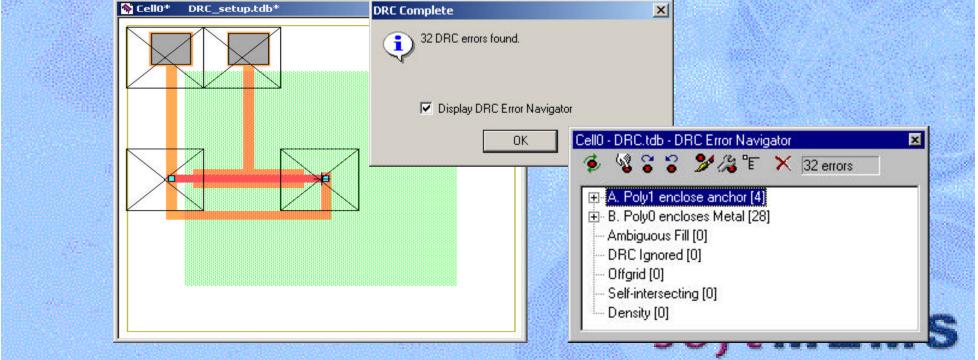
#### **Basic Bricks at the** Layout Level

- Design Rules Checking
- Parameters and Parasitic Extractions
- Layout Versus Schematic



## **DRC-** Design Rule Checking

- DRC set up to check manufacturing rules, spacing, surround, size, etc.
- Supports context sensitive rules- e.g. Number of etch holes per area on plates necessary to make sure plate is released.
- Supports device specific rules e.g. placement of stator over ground plane on motor



- 3D Modeling
- Device is accompanied by listing of relevant parameters- geometry or higher level C, N of. Comb fingers etc.
- Extraction also produces a set of lumped parasitic elements capacitances and resistances on each signal or control line
- Values are computed from the geometry and process variables- layer thickness and dielectric constants softMEMS

#### **ROUND TABLE ON MICRO/NANO TECHNOLOGIES FOR SPACE 5**<sup>TH</sup>

## October 3-5, 2005, Noordwijk, The Netherlands

